

3M Scotch-Weld™ Epoxy Potting Compound/Adhesive DP270 Clear and Black

Technical Data

March, 2015

Product Description

3M™ Scotch-Weld™ Epoxy Potting Compound/Adhesive DP270 (or 3M™ Scotch-Weld™ Epoxy Potting Compound/Adhesive 270 B/A) is a two-part, low viscosity epoxy resin system designed primarily for potting, sealing, and encapsulation of many electronic components and is available in clear or black. Scotch-Weld epoxy potting compound/adhesive DP270 is noncorrosive to copper and offers good thermal shock resistance and excellent retention of electrical insulation properties under high humidity conditions.

3M™ Scotch-Weld™ epoxy potting compound/adhesive DP270 has a work life of approximately 70 minutes, a tack-free time of about 3 hours and is fully cured after 48 hours at 73°F (23°C). This product produces no exotherm in 5-10 gram masses and a very slight exotherm in larger masses.

3M™ Scotch-Weld™ epoxy potting compound/adhesive DP270 is ideal for the potting and encapsulation of many heat sensitive or delicate components such as glass diodes and sensors as well as for transformers, coils, chokes, relays, etc. It is available in the convenient 3M™ EPX™ Applicator System for multi-station usage and in bulk containers for larger volume applications.

Available in bulk containers as Scotch-Weld epoxy potting compound/adhesive 270 B/A.

Features

- Good Thermal Shock Resistance
- Meets UL 94 HB (File No. E61941)
- Long Worklife
- Excellent Electrical Properties
- Noncorrosive to Copper
- Negligible Exotherm

Typical Uncured Properties

Note: The following technical information and data should be considered representative or typical only and should not be used for specification purposes.

Color:	Clear or Black
Base Resin:	Epoxy/amine
Mix Ratio:	1:1 by volume (1:0.85 B:A by weight)
Net Weight: Lbs./Gal.	Base 9.6 - 9.7 Accelerator 8.0 - 8.2
Worklife:	60-70 minutes @ 23°C (73°F)
Viscosity: @ 23°C (73°F)	Base 7000 - 16,000 cps Accelerator 6000 - 12,000 cps

3M™ Scotch-Weld™ Epoxy Potting Compound/Adhesive DP270 Clear and Black

Typical Cured Properties

Note: The following technical information and data should be considered representative or typical only and should not be used for specification purposes.

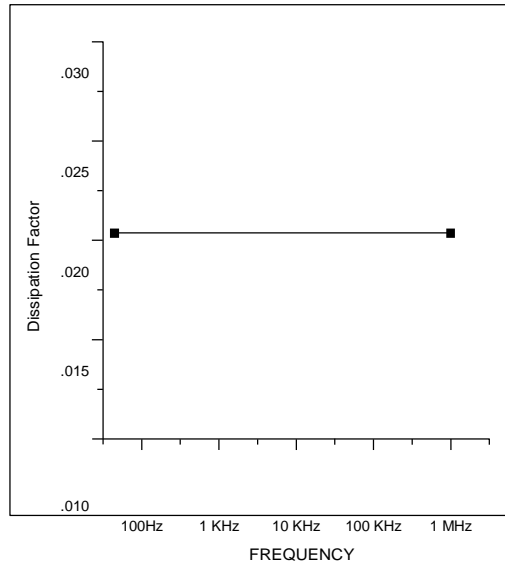
Physical:	
Color	Clear or Black
Refractive Index @ 25°C (77°C)	Clear 1.656
Cure Shrinkage	.08%
Shore D Hardness (ASTM D-2240)	83
Tack-free Time	Approx. 3 hrs. @ 23°C (73°F)
UL Rating	94 HB (File No. E61941)
Cure Time	48 hrs. @ 23°C (73°F)
Thermal:	
Weight Loss by TGA (in air)	1% @ 122°C (252°F) 5% @ 175°C (347°F) 10% @ 210°C (410°F)
Thermal Coefficient of Expansion by TMA	
Below Tg	80 x 10 ⁻⁶ units/unit/°C 5-30°C range (10-86°F range)
Above Tg	180 x 10 ⁻⁶ units/unit/°C 60-125°C range (140-257°F)
Glass Transition Temperature by DSC	
Onset	43°C (109°F)
Mid-Point	49°C (120°F)
Thermal Conductivity (@ 110°F on .250" samples)	
BTU - ft./ft. ² - hr. - °F	.103
Cal./sec. - cm - °C	.426 x 10 ³
Watt/m - °C	.177
Thermal Shock Resistance	
Potted Washer Olyphant Test 3M Test Method C-3174 +100°C (air) to -50°C (liquid)	Pass 5 Cycles without cracking
Electrical:	
Dielectric Constant (ASTM D-150)	3.5 @ 1 KHz @ 23°C (73°F)
Dissipation Factor (ASTM D-150)	.018 @ 1 KHz @ 23°C (73°F)
Dielectric Strength (ASTM D-149)	850 volts/mil
Volume Resistivity (ASTM D-257)	4.1 x 10 ¹⁴ ohm-cm
Insulation Resistance (.8 mm/.8 mm comb pattern on FR-4) 60°C/96% R.H./100 volts d.c.)	
Initial	3 x 10 ¹³ ohms
1000 hrs.	2 x 10 ¹¹ ohms

3M™ Scotch-Weld™ Epoxy Potting Compound/Adhesive DP270 Clear and Black

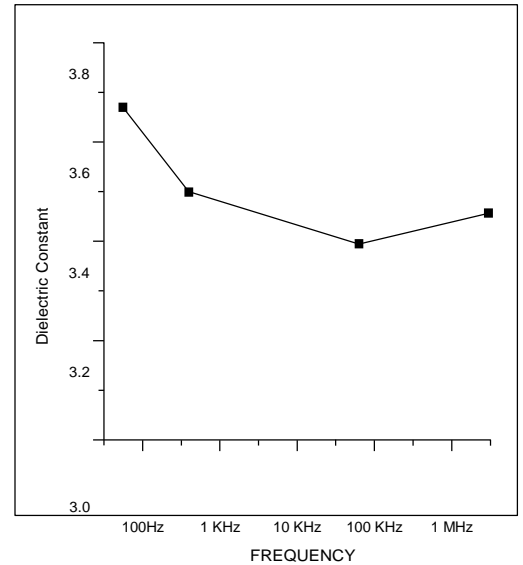
Additional Electrical Properties

Note: The following technical information and data should be considered representative or typical only and should not be used for specification purposes.

Dissipation Factor Versus Frequency

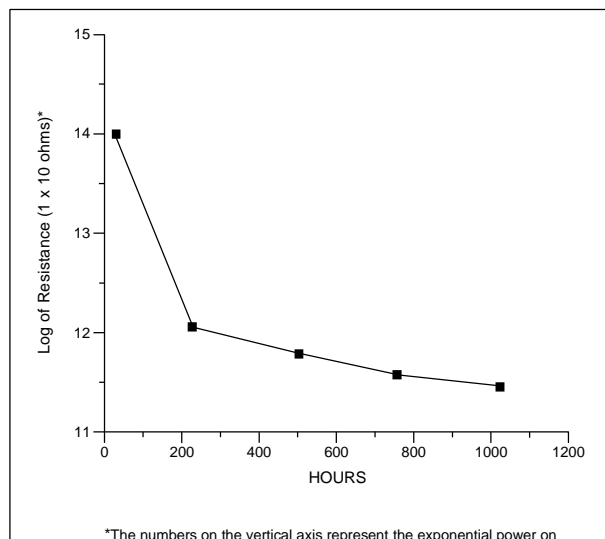


Dielectric Constant Versus Frequency



Insulation Resistance

.8 mm/.8 mm Comb Pattern
60°C (140°F)/95% RH/100 V d.c.



3M™ Scotch-Weld™ Epoxy Potting Compound/Adhesive DP270 Clear and Black

Typical Cured Properties (continued)

Note: The following technical information and data should be considered representative or typical only and should not be used for specification purposes.

Corrosion:		
Per ASTM D-3482 (35°C/95°F/96% R.H./45V d.c./15 days)		Pass - No copper corrosion
Per 3M Test Method C-708 (45°C/113°F/96% R.H./250V d.c./5 days)		Pass - No copper corrosion
(65°C/149°F/96% R.H./250V d.c./4 days)		Pass - No copper corrosion
Per Mil S-46163 (10 days/50% R.H./23°C/73°F)		Pass - No aluminum, brass or steel discoloration or corrosion
Solvent Resistance:		
(Visual check after immersion in specified solvent at 23°C (73°F))		
	1 Hour	1 Month
Acetone	B	C
Isopropyl Alcohol	A	B
Freon TF	A	A
Freon TMC	B	C
1,1,1-Trichloroethane	A	C
RMA Flux	A	B
Key: A - Unaffected B - Slight Attack C - Moderate/Severe Attack		

Typical Adhesive Performance Characteristics

Note: The following technical information and data should be considered representative or typical only and should not be used for specification purposes.

Although 3M™ Scotch-Weld™ Epoxy Potting Compound/Adhesive DP270 and 270 B/A can be used for many potting and encapsulation applications, they can also be used as adhesives. The following shows typical shear and peel values determined on several common substrates:

Overlap Shear Adhesion (ASTM D-1002-72)

	Curing Conditions 7 days/73°F (23°C)	
Alum./Alum. (etched)	@-67°F (-55°C) @73°F (23°C) @180°F (82°C)	1200-1250 psi 2450-2500 psi 300-350 psi
FR-4/FR-4 (MEK Wiped)	@73°F (23°C)	1750-1800 psi
Copper/Copper (MEK Wiped)	@73°F (23°C)	1700-1750 psi

90° T-Peel Adhesion (ASTM D-1876-61T)

Alum./Alum. (etched)	@73°F (23°C)	< 2 piw
----------------------	--------------	---------

Compression Strength (ASTM D-695-68T)

Scotch-Weld epoxy potting compound/adhesive DP270 Clear and Black	@73°F (23°C)	8100 psi
--	--------------	----------

3M™ Scotch-Weld™ Epoxy Potting Compound/Adhesive DP270 Clear and Black

3M™ EPX™ Pneumatic Applicator Delivery Rates

200 ml Applicator – Maximum Pressure 58 psi

Adhesive*	6mm Nozzle gms/minute	10mm Nozzle gms/minute
3M™ Scotch-Weld™ Epoxy Potting Compound/Adhesive DP270 Black	38.2	148.8

50 ml Applicator – Maximum Pressure 50 psi

Adhesive*	1/4 in. Nozzle gms/minute
3M™ Scotch-Weld™ Epoxy Potting Compound/Adhesive DP270 Clear	75.6
Scotch-Weld epoxy potting compound/adhesive DP270 Black	68.6

*Tests were run at a temperature of 70°F ± 2°F (21°C ± 1°C) and at maximum applicator pressure.

Handling/Curing Information

Directions for Use

1. For high strength structural bonds, paint, oxide films, oils, dust, mold release agents and all other surface contaminants must be completely removed. However, the amount of surface preparation directly depends on the required bond strength and the environmental aging resistance desired by user. For specific surface preparations on common substrates, see the section on surface preparation.
2. These products consist of two parts.

Mixing

For Duo-Pak Cartridges

3M™ Scotch-Weld™ epoxy potting compound/adhesive DP270 Clear and Black are supplied in a dual syringe plastic duo-pak cartridge as part of the 3M™ EPX™ Applicator systems. To use, simply insert the duo-pak cartridge into the EPX applicator and start the plunger into the cylinders using light pressure on the trigger. Next, remove the duo-pak cartridge cap and expel a small amount of adhesive to be sure both sides of the duo-pak cartridge are flowing evenly and freely. If mixing of Part A and Part B is desired, attach the EPX applicator mixing nozzle to the duo-pak cartridge and begin dispensing the adhesive. For hand mixing, expel the desired amount of material and mix thoroughly to obtain a uniform color.

For Bulk Containers

Mix thoroughly by weight or volume in the proportions specified in the typical uncured properties section to obtain a uniform color.

3M™ Scotch-Weld™ Epoxy Potting Compound/Adhesive DP270 Clear and Black

Handling/Curing Information (*continued*)

3. For maximum bond strength apply product evenly to both surfaces to be joined.
4. Application to the substrates should be made within 70 minutes. Larger quantities and/or higher temperatures will reduce this working time.
5. Join the adhesive coated surfaces and allow to cure at 60°F (16°C) or above until firm. Heat up to 200°F (93°C) will speed curing.
6. The following times and temperatures will result in a full cure of these products.

23°C (73°F)	48 Hours
50°C (122°F)	4 Hours
80°C (176°F)	60 Minutes
100°C (212°F)	30 Minutes
7. Keep parts from moving during cure. Contact pressure necessary. Maximum shear strength is obtained with a 3-5 mil bond line.
8. Excess uncured adhesive can be cleaned up with ketone type solvents*.

***Note:** When using solvents, extinguish all ignition sources, including pilot lights, and follow the manufacturer's precautions and directions for use.

Adhesion Coverage: A 0.005 in. thick bondline will yield a coverage of 320 sq. ft./gallon

Application and Equipment Suggestions

These products may be applied by spatula, trowel or flow equipment.

Two part mixing/proportioning/dispensing equipment is available for intermittent or production line use. These systems are ideal because of their variable shot size and flow rate characteristics and are adaptable to most applications.

3M™ Scotch-Weld™ Epoxy Potting Compound/Adhesive DP270 Clear and Black

Surface Preparation

For high strength structural bonds, paint, oxide films, oils, dust, mold release agents and all other surface contaminants must be completely removed. However, the amount of surface preparation directly depends on the required bond strength and the environmental aging resistance desired by user.

The following cleaning methods are suggested for common surfaces:

Steel

1. Wipe free of dust with oil-free solvent such as acetone, isopropyl or alcohol solvents.*
2. Sandblast or abrade using clean fine grit abrasives.
3. Wipe again with solvent to remove loose particles.
4. If a primer is used, it should be applied within 4 hours after surface preparation.

Aluminum

1. Alkaline Degrease: Oakite 164 solution (9-11 oz./gallon water) at 190°F ± 10°F (88°C ± 5°C) for 10-20 minutes. Rinse immediately in large quantities of cold running water.
2. Acid Etch: Place panels in the following solution for 10 minutes at 150°F ± 5°F (66°C ± 2°C).

Sodium Dichromate	4.1 - 4.9 oz./gallon
Sulfuric Acid, 66°Be	38.5 - 41.5 oz./gallon
2024-T3 aluminum (dissolved)	0.2 oz./gallon minimum
Tap water as needed to balance	

3. Rinse: Rinse panels in clear running tap water.
4. Dry: Air dry 15 minutes; force dry 10 minutes at 150°F ± 10°F (66°C ± 5°C).
5. If primer is to be used, it should be applied within 4 hours after surface preparation.

Plastics/Rubber

1. Wipe with isopropyl alcohol.*
2. Abrade using fine grit abrasives.
3. Wipe with isopropyl alcohol.*

Glass

1. Solvent wipe surface using acetone or MEK.*
2. Apply a thin coating (0.0001 in. or less) of 3M™ Scotch-Weld™ Metal Primer EC3901 to the glass surfaces to be bonded and allow the primer to dry 60 minutes before bonding.

***Note:** When using solvents, extinguish all ignition sources, including pilot lights, and follow the manufacturer's precautions and directions for use.

3M™ Scotch-Weld™ Epoxy Potting Compound/Adhesive DP270 Clear and Black

Storage Store product at 60-80°F (16-27°C) for maximum storage life.

Shelf Life These products when stored in original, unopened container have a shelf life of two years for bulk containers and 15 months in duo-pak containers.

Precautionary Information Refer to Product Label and Material Safety Data Sheet for health and safety information before using this product. For additional health and safety information, call 1-800-364-3577 or (651) 737-6501.

Technical Information The technical information, recommendations and other statements contained in this document are based upon tests or experience that 3M believes are reliable, but the accuracy or completeness of such information is not guaranteed.

Product Use Many factors beyond 3M's control and uniquely within user's knowledge and control can affect the use and performance of a 3M product in a particular application. Given the variety of factors that can affect the use and performance of a 3M product, user is solely responsible for evaluating the 3M product and determining whether it is fit for a particular purpose and suitable for user's method of application.

Warranty, Limited Remedy, and Disclaimer Unless an additional warranty is specifically stated on the applicable 3M product packaging or product literature, 3M warrants that each 3M product meets the applicable 3M product specification at the time 3M ships the product. 3M MAKES NO OTHER WARRANTIES OR CONDITIONS, EXPRESS OR IMPLIED, INCLUDING, BUT NOT LIMITED TO, ANY IMPLIED WARRANTY OR CONDITION OF MERCHANTABILITY OR FITNESS FOR A PARTICULAR PURPOSE OR ANY IMPLIED WARRANTY OR CONDITION ARISING OUT OF A COURSE OF DEALING, CUSTOM OR USAGE OF TRADE. If the 3M product does not conform to this warranty, then the sole and exclusive remedy is, at 3M's option, replacement of the 3M product or refund of the purchase price.

Limitation of Liability Except where prohibited by law, 3M will not be liable for any loss or damage arising from the 3M product, whether direct, indirect, special, incidental or consequential, regardless of the legal theory asserted, including warranty, contract, negligence or strict liability.

ISO 9001:2000

This Industrial Adhesives and Tapes Division product was manufactured under a 3M quality system registered to ISO 9001:2000 standards.

3M Industrial Adhesives and Tapes Division

3M Center, Building 225-3S-06
St. Paul, MN 55144-1000
800-362-3550 • 877-369-2923 (Fax)
www.3M.com/structuraladhesives

3M, Scotch-Weld and EPX are
trademarks of 3M Company.
©3M 2015

Данный компонент на территории Российской Федерации

Вы можете приобрести в компании MosChip.

Для оперативного оформления запроса Вам необходимо перейти по данной ссылке:

<http://moschip.ru/get-element>

Вы можете разместить у нас заказ для любого Вашего проекта, будь то серийное производство или разработка единичного прибора.

В нашем ассортименте представлены ведущие мировые производители активных и пассивных электронных компонентов.

Нашей специализацией является поставка электронной компонентной базы двойного назначения, продукции таких производителей как XILINX, Intel (ex.ALTERA), Vicor, Microchip, Texas Instruments, Analog Devices, Mini-Circuits, Amphenol, Glenair.

Сотрудничество с глобальными дистрибьюторами электронных компонентов, предоставляет возможность заказывать и получать с международных складов практически любой перечень компонентов в оптимальные для Вас сроки.

На всех этапах разработки и производства наши партнеры могут получить квалифицированную поддержку опытных инженеров.

Система менеджмента качества компании отвечает требованиям в соответствии с ГОСТ Р ИСО 9001, ГОСТ РВ 0015-002 и ЭС РД 009

Офис по работе с юридическими лицами:

105318, г.Москва, ул.Щербаковская д.3, офис 1107, 1118, ДЦ «Щербаковский»

Телефон: +7 495 668-12-70 (многоканальный)

Факс: +7 495 668-12-70 (доб.304)

E-mail: info@moschip.ru

Skype отдела продаж:

moschip.ru

moschip.ru_4

moschip.ru_6

moschip.ru_9